

CLAIMS

What is claimed is:

1 1. An integrated circuit package, comprising:
2 a substrate;
3 an integrated circuit mounted to said substrate;
4 a thermal element located adjacent to said integrated
5 circuit; and,
6 an epoxy that is attached to said integrated circuit
7 and said thermal element, said epoxy being cured by
8 energy at a microwave frequency.

1 2. The package of claim 1, further comprising a
2 solder ball attached to said substrate.

1 3. The package of claim 1, further comprising a
2 solder bump attached to said integrated circuit and said
3 substrate.

1 4. The package of claim 1, further comprising an
2 encapsulant that encloses said integrated circuit.

1 5. A method for assembling an integrated circuit
2 package, comprising:
3 applying an epoxy to an integrated circuit;
4 placing a thermal element adjacent to the epoxy; and,

5 curing the epoxy with energy at a microwave
6 frequency.

1 6. The method of claim 5, further comprising the
2 step of mounting the integrated circuit to a substrate.

1 7. The method of claim 6, further comprising the
2 step of attaching a solder ball to the substrate.

1 8. The method of claim 5, further comprising the
2 step of molding an encapsulant onto the substrate and the
3 integrated circuit.

1 9. A method for assembling an integrated circuit
2 package, comprising:

3 applying an epoxy to a thermal element;

4 placing the epoxy and the thermal element onto an
5 integrated circuit; and,

6 curing the epoxy with energy at a microwave
7 frequency.

Sub A3 10. The method of claim 9, further comprising the
2 step of mounting the integrated circuit to a substrate.

Sub A4 11. The method of claim 10, further comprising the
2 step of attaching a solder ball to the substrate.

Sub A5 >

12. The method of claim 9, further comprising the
2 step of molding an encapsulant onto the substrate and the
3 integrated circuit.

Add A6 >

042390.P6785